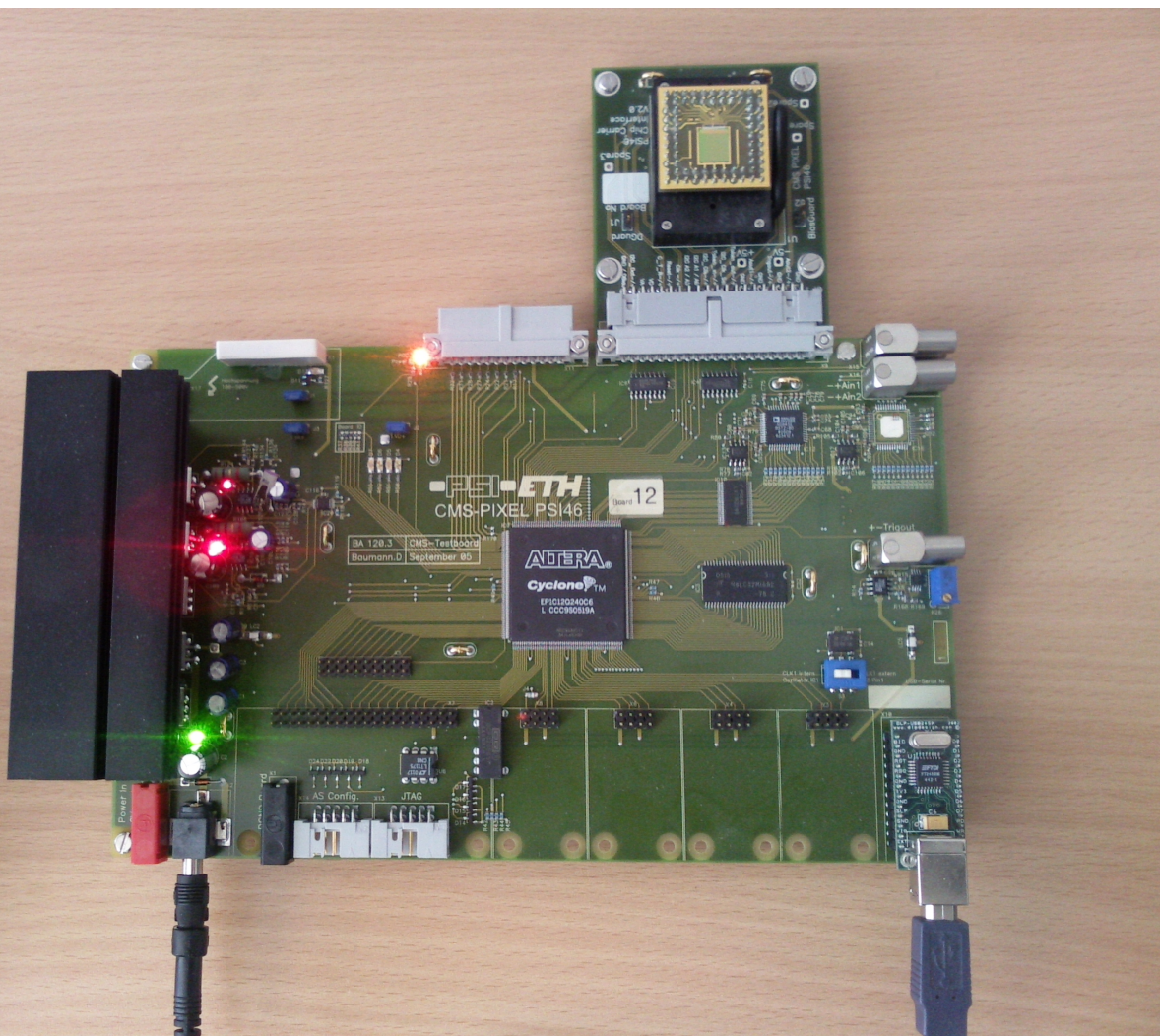


# New CMS Pixel Test Board Adapter

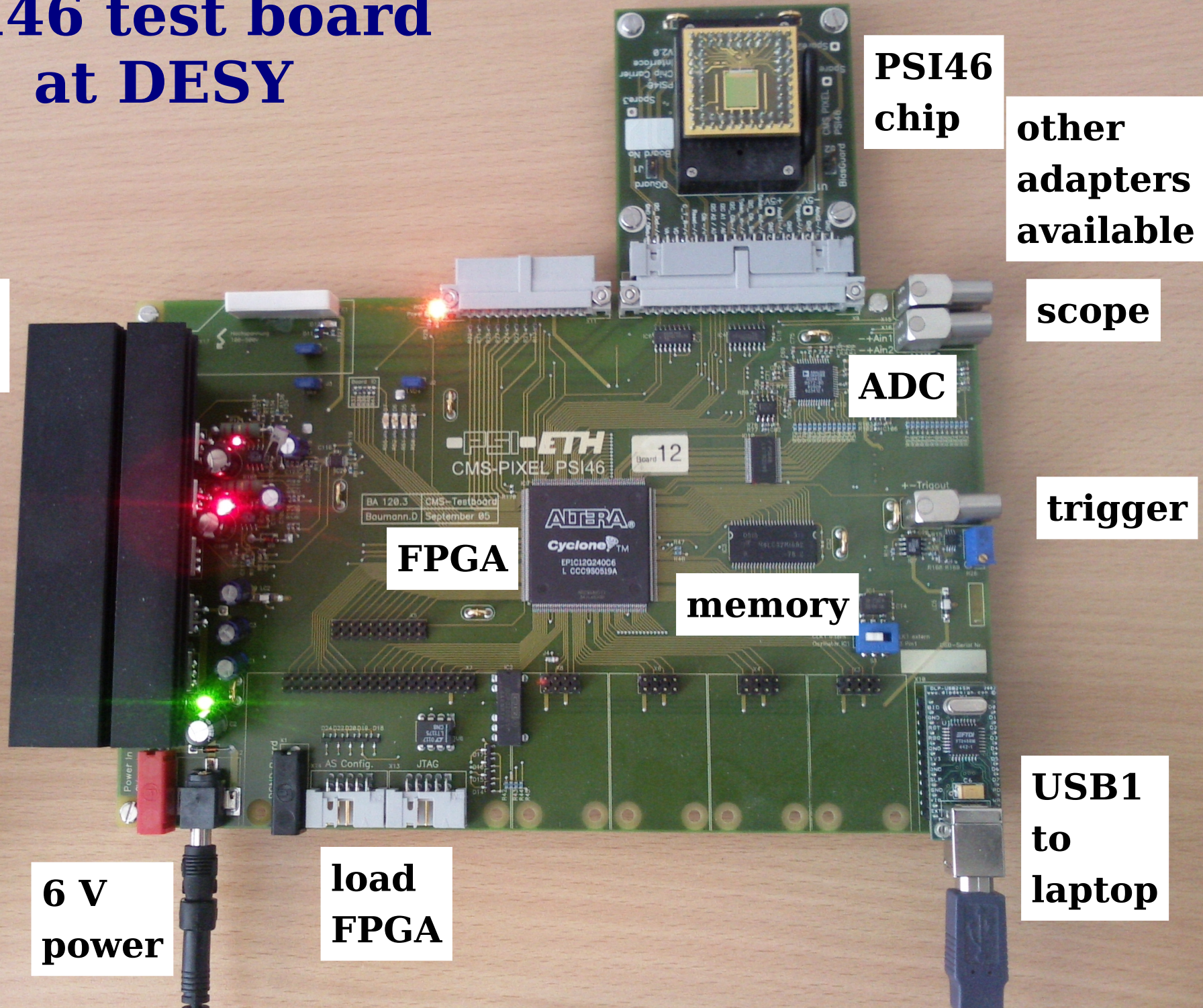
Daniel Pitzl, DESY  
Pixel upgrade, 1.11.2011



- Test board
- New adapter

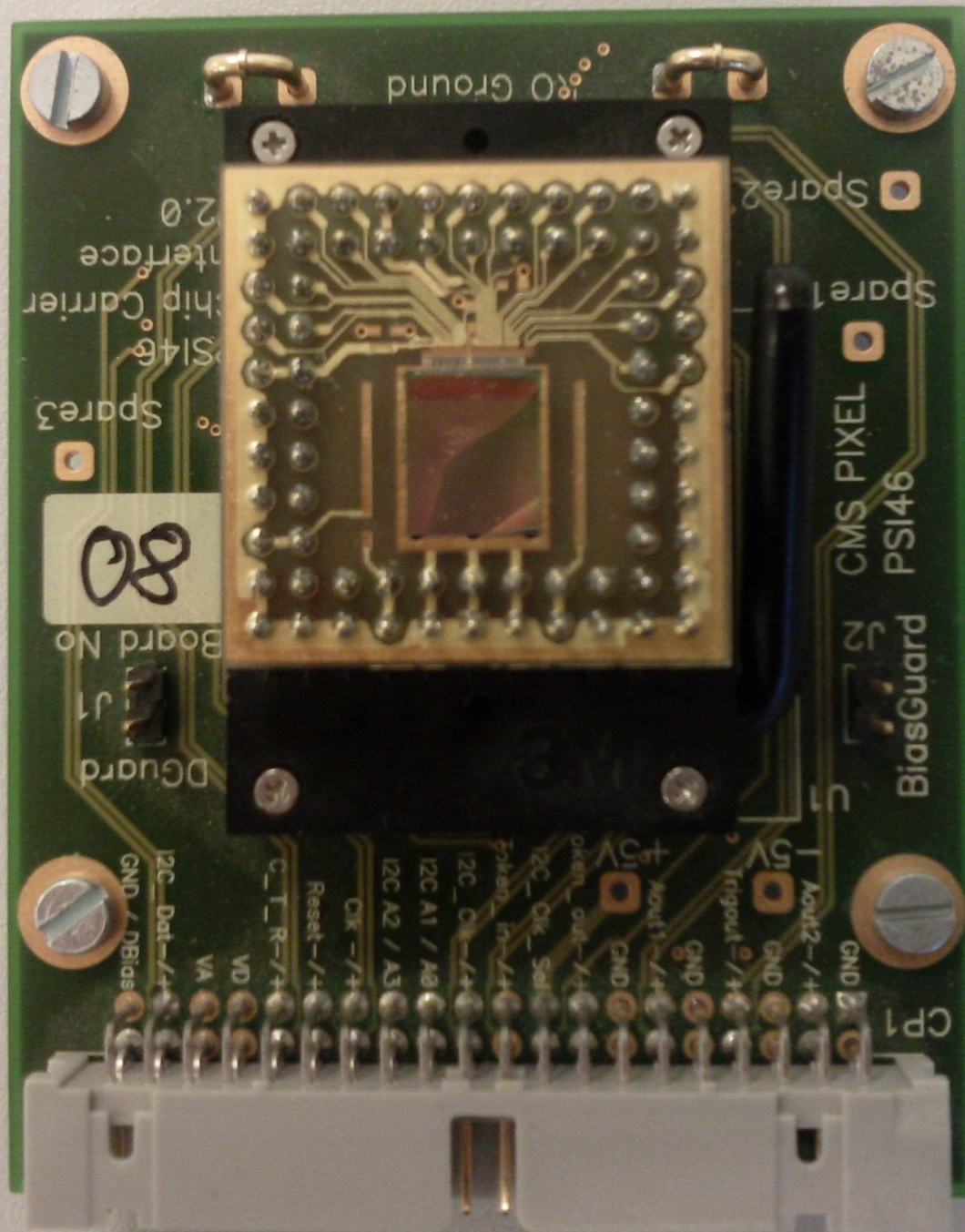


# PSI46 test board at DESY





# Present ROC adapter





# Test board connector

X9					
Dir	Name	PIN		Name	Dir
	<i>nc</i>	1	2	<i>GND</i>	
IN	<i>AOUT2-</i>	3	4	<i>AOUT2+</i>	IN
	<i>GND</i>	5	6	<i>GND</i>	
IN	<i>TRIGOUT-</i>	7	8	<i>TRIGOUT+</i>	IN
	<i>GND</i>	9	10	<i>GND</i>	
IN	<i>AOUT1-</i>	11	12	<i>AOUT1+</i>	IN
	<i>GND</i>	13	14	<i>GND</i>	
IN	<i>TOUT-</i>	15	16	<i>TOUT+</i>	IN
	<i>+5V</i>	17	18	<i>CLK_SEL</i>	OUT
OUT	<i>TIN-</i>	19	20	<i>TIN+</i>	OUT
OUT	<i>I2C_CLK-</i>	21	22	<i>I2C_CLK+</i>	OUT
OUT	<i>A0</i>	23	24	<i>A1</i>	OUT
OUT	<i>A2</i>	25	26	<i>A3</i>	OUT
OUT	<i>CLK_ROC-</i>	27	28	<i>CLK_ROC+</i>	OUT
	<i>nc</i>	29	30	<i>#RESET</i>	OUT
OUT	<i>CTR-</i>	31	32	<i>CTR+</i>	OUT
OUT	<i>VD+</i>	33	34	<i>VD+</i>	OUT
OUT	<i>VA+</i>	35	36	<i>VA+</i>	OUT
OUT	<i>I2C_DAT-</i>	37	38	<i>I2C_DAT+</i>	OUT
OUT	<i>BIAS_GND</i>	39	40	<i>BIAS</i>	OUT



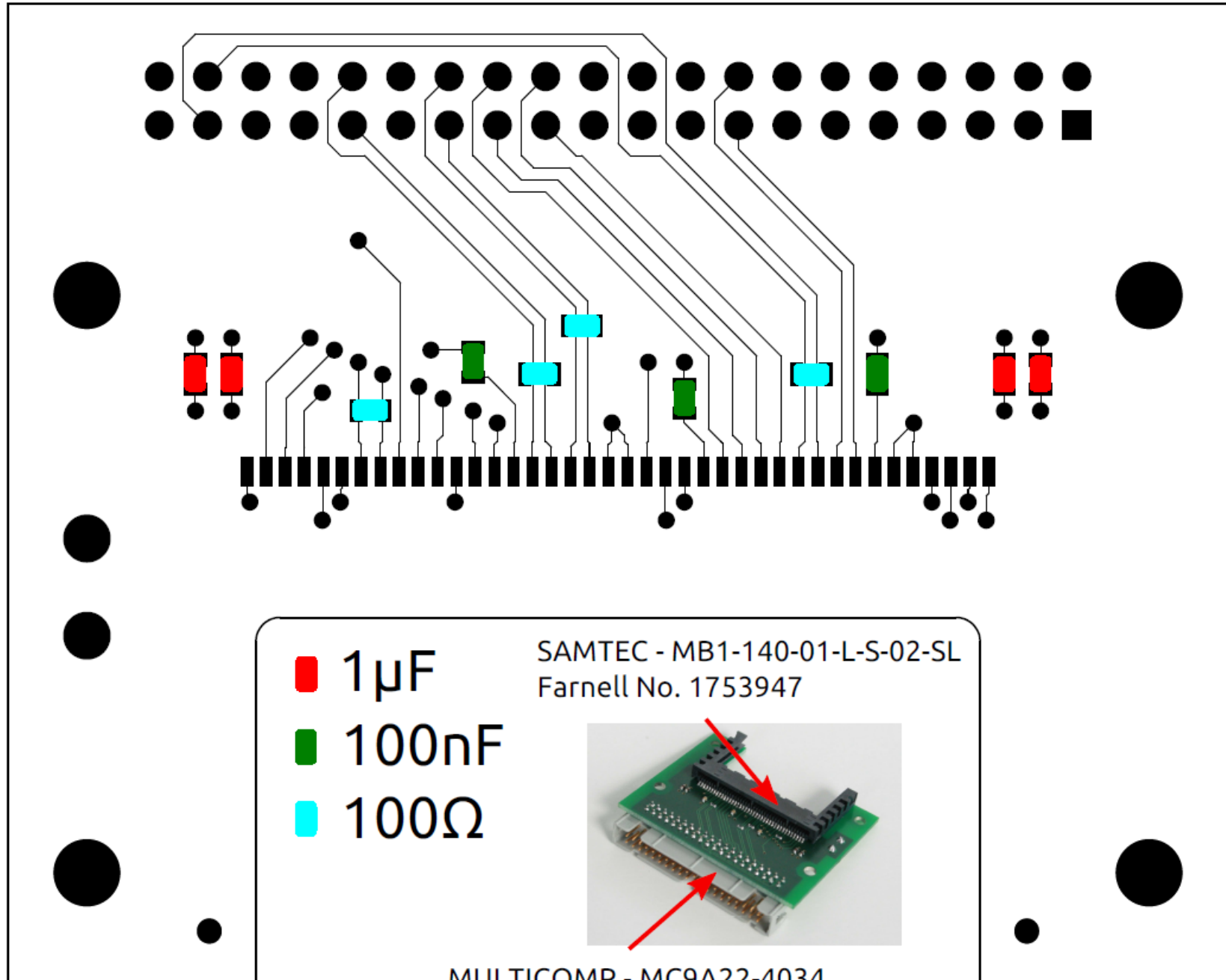
**Beat Meier  
2007**

# New chip adapter cards needed

- DESY will receive new chips from PSI
- They need to be mounted:
  - glue to a carrier, wire bond, attach to a test board.
- old zif sockets:
  - expensive, labor-intensive to assemble,
  - lots of dead material in a test beam.
- New edge connector design from PSI:
  - Chip glued directly to simple PCB (no SMD components)
  - Need to add Vbias line
  - Produce many
- Requires one interface card per test board
  - with SMD components
  - add Vbias line

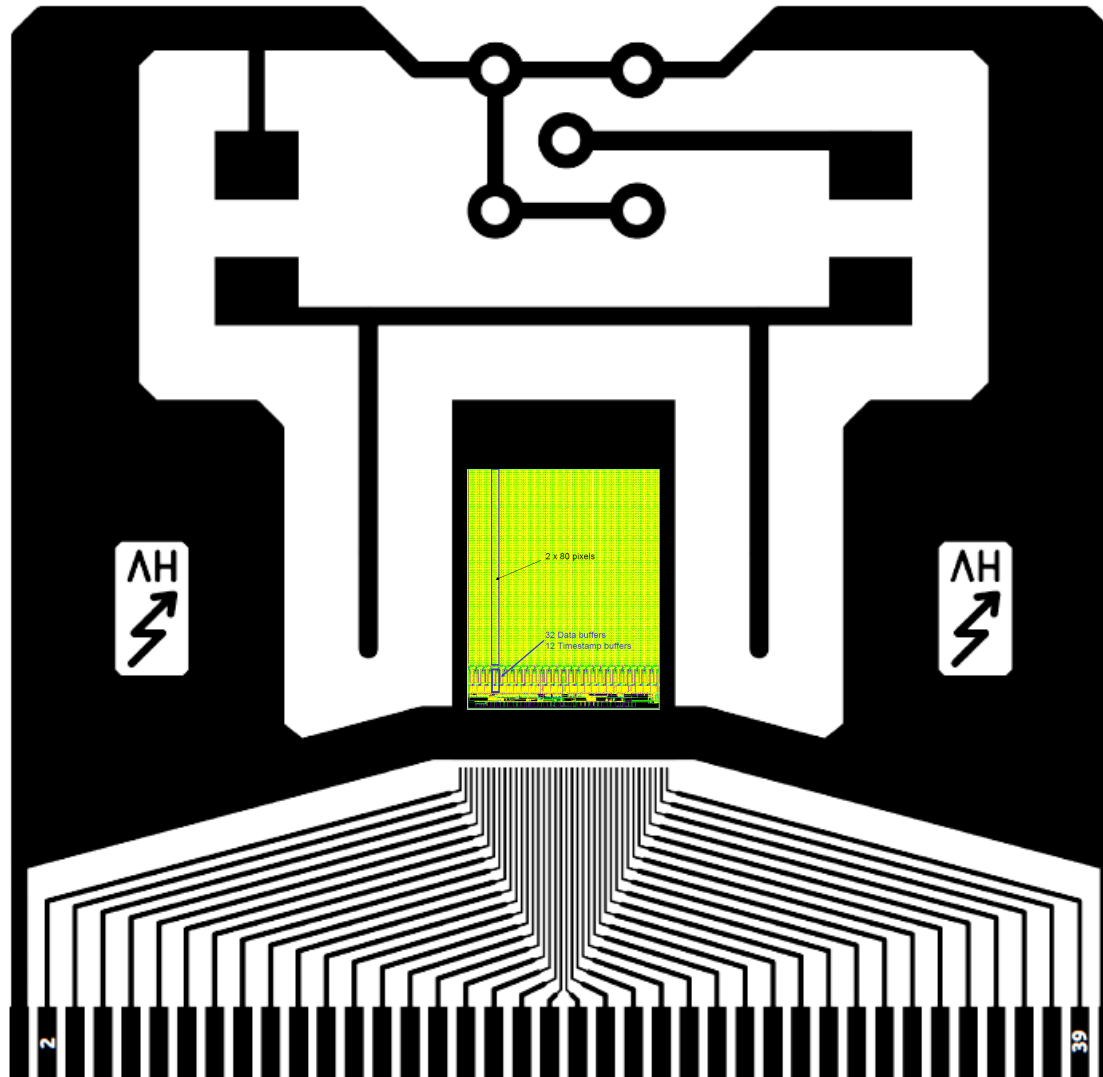
# New interface cards

add  
Vbias  
line



Silvan  
Streuli  
PSI  
2011

# New adapter cards



**sensor Vbias  
on Lemo  
connector**

**ROC:  
glue and  
wire bond.**

**add Vbias  
line to  
test board**

**into edge connector  
on new interface card**

**Silvan  
Streuli  
PSI  
2011**

# Wire bond plan

Silvan  
Streuli  
PSI  
2011

add  
Vbias  
line

